

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

**Claims 1-22 (Cancelled without prejudice or disclaimer).**

23. (New) A wireless identification semiconductor device comprising:  
a first conductor;  
a second conductor; and  
an IC chip;  
wherein at least one of first and second conductors serves as an antenna;  
wherein the IC chip includes a first electrode formed on a front surface of the IC chip, a second electrode formed on a rear surface of the IC chip and a rectifier circuit comprising a first diode, a second diode and a capacitor;  
wherein a first end of the capacitor is coupled to the first electrode;  
wherein a second end of the capacitor is coupled to a cathode of the first diode and an anode of the second diode;  
wherein an anode of the first diode is coupled to the second electrode which is the same potential as that of a substrate of the IC chip;  
wherein a slit is provided which extends in a direction of a longitudinal axis of at least one of the first and second conductors from a central part of said one of the first and second conductors;

wherein the IC chip is coupled between the first conductor and the second conductor through the first electrode and the second electrode; and  
wherein the other of the first and second conductors crosses over the slit and is coupled to said one of the first and second conductors.

24. (New) The wireless identification semiconductor device according to claim 23;

wherein the first diode and second diode are each comprised of a diode-connected capacitor having a gate and a drain connected to one another.

25. (New) The wireless identification semiconductor device according to claim 23;

wherein the capacitor is a MOS-capacitor including a gate which corresponds to one end of the capacitor, and a drain or a source corresponding to another end of the capacitor.

26. (New) The wireless identification semiconductor device according to claim 23;

wherein the IC chip is coupled between the first conductor and the second conductor through an anisotropic conductive adhesive.

27. (New) The wireless identification semiconductor device according to  
claim 23;

wherein said at least one of the first and second conductors comprises a  
tabular dipole antenna.

28. (New) The wireless identification semiconductor device according to  
claim 23,

wherein the slit is provided in the second conductor and the first conductor  
crosses over the slit.